

Product Specification

CUSTOMER: _____

DESCRIPTION: _____

RF TRANSFORMER

MNC P/N: _____

RFT-138SG

REVISION: _____

X0

CUSTOMER P/N: _____

ISSUED DATE: _____

2017-05-22

PHOTO OF
PRODUCT: _____

WEIGHT: _____

0.057g

PREPARED BY	CHECKED BY	APPROVED BY
Jimmy Huang	Sonny Zhang	CW Wang

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CHANGE RECORD

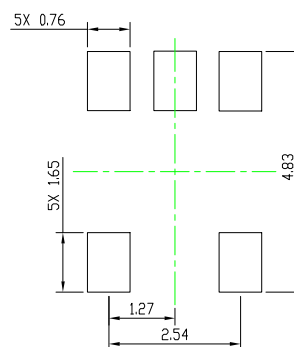
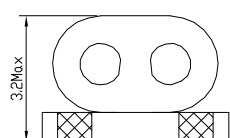
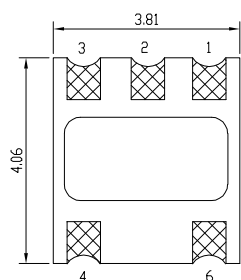
REV.	DESCRIPTION (Content or Reason For Change)	DATE	REVISER
X0	INITIAL RELEASE	2017-05-22	Jimmy Huang

- RF Transformer
- Operating Temperature Range: -40 °C to +85 °C
- Storage Temperature Range: -55 °C to +100 °C
- RoHS Compliant

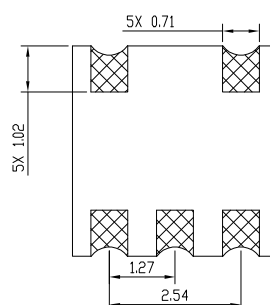
Electrical Specifications @25°C, Z₀=75Ω

Part Number	Ω Ratio	Insertion Loss		Amplitude Balance		Phase Balance		Frequency Range
	Pri:Sec (P1-3:P4-6)	5-300MHz	5-1200MHz	5-500MHz	5-1200MHz	5-500MHz	5-1200MHz	
RFT-138SG	1:3	1.0dB Max	2.0dB Max	±0.5dB Max	±1.5dB Max	±2° Max	±15° Max	5-1200MHz

MECHANICAL DIMENSIONS(units:mm)

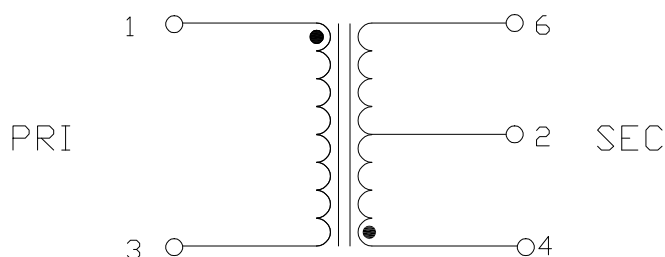


Recommended PAD Layout

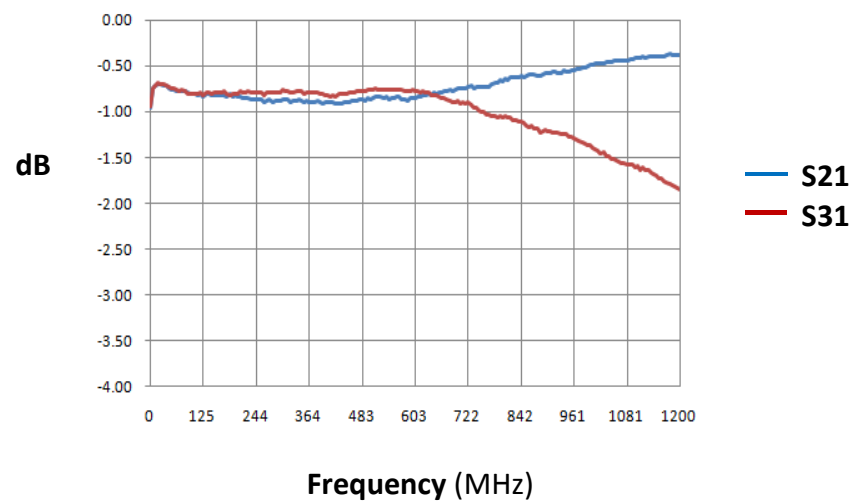


Unless otherwise specified all tolerances are:±0.25 mm

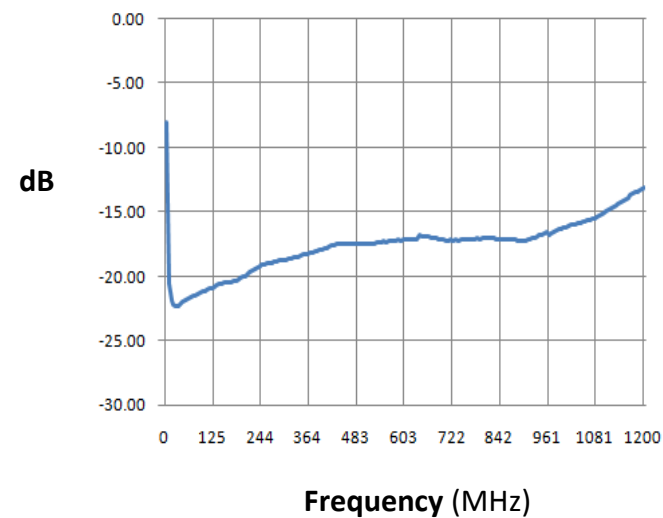
SCHEMATIC



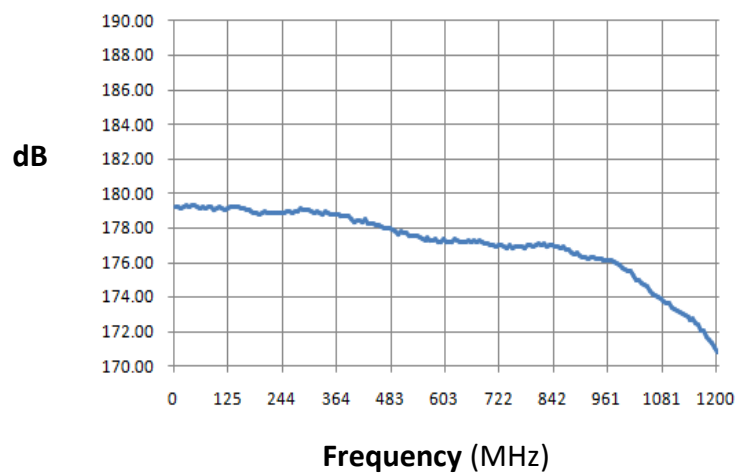
Insertion Loss



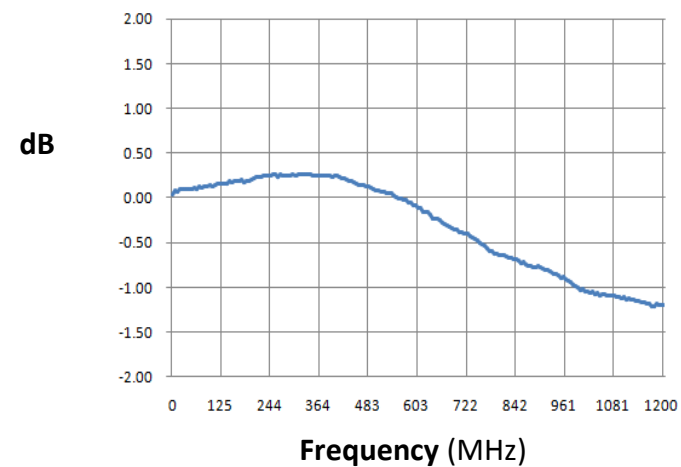
Input Return Loss



Phase Balance

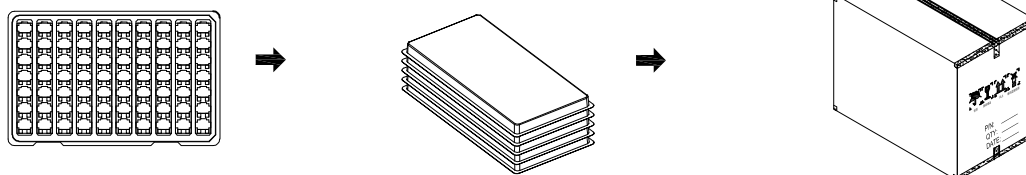


Amplitude Balance



PACKING:

☐ Tray:

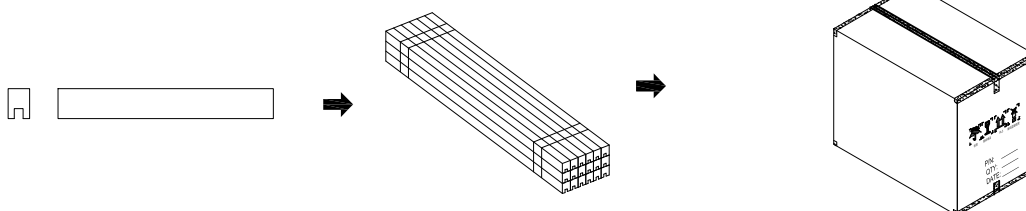


Q'ty

_____ PCS Per Tray

_____ PCS Per Carton

☐ Tube:

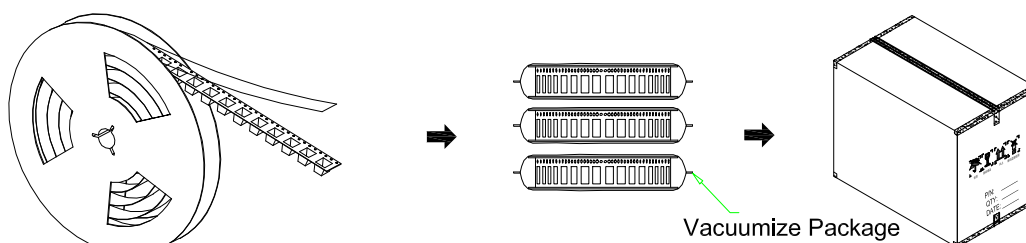


Q'ty

_____ PCS Per Tube

_____ PCS Per Carton

☒ Reel:



Q'ty

2500 PCS Per Reel

30000 PCS Per Carton

MOISTURE SENSITIVE LEVEL:

1. Level:1

2.Shelf Life:Unlimited

3.Storage Condition:<=30℃/85% RH

RECOMMENDED SOLDERING PROFILE:

☒ 1. Reflow soldering profile(According to IPC/JEDEC J-STD-020C)

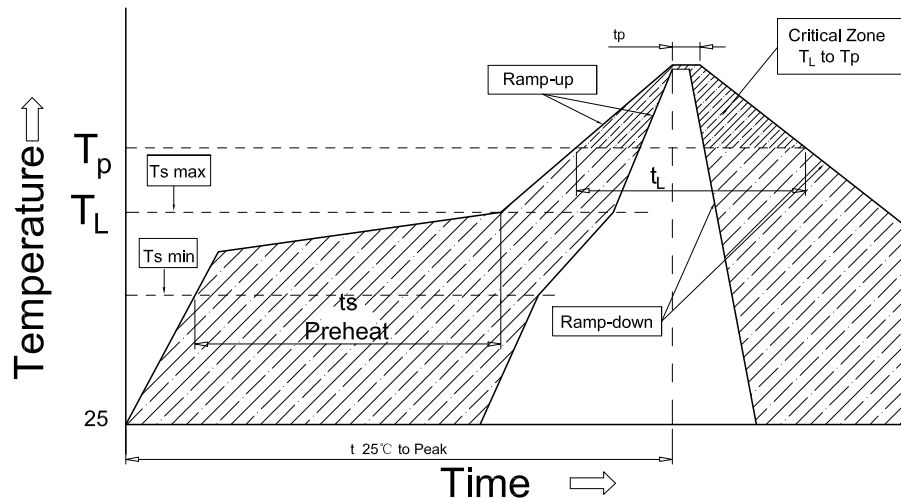


Table 1-1 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate ($T_{s\max}$ to T_p)	3°C/second max	3°C/second max
Preheat		
-Temperature Min ($T_{s\min}$)	100°C	150°C
-Temperature Max ($T_{s\max}$)	150°C	200°C
-Time ($t_{s\min}$ to $t_{s\max}$)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T_L)	183°C	217°C
-Time (t_L)	60-150 seconds	60-150 seconds
Peak/Classification Temperature(T_p)	See IPC/JEDEC J-STD-020C Table 4-1	See IPC/JEDEC J-STD-020C Table 4-2
Time within 5°C of actual Peak Temperature(t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max	8 minutes max

Note1: All temperatures refer to topside of the package, measured on the package body surface

- Suggested soldering process: Reflow soldering
- Solder Paste: Sn96.5Ag3.0Cu0.5
- Silkscreen thickness: 0.15mm Min.

☐ 2. Wave soldering profile

